


THE UNIVERSITY OF CHICAGO

Respectfully submitted,

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By 

APPENDIX

3. (amended) A method as claimed in claim ~~1 or 2~~, characterized in that prior to the formation of the electrically conductive vias (5) and prior to the provision of the semiconductor body (1) on the flexible foil (6) that is detachably secured to the substrate (7), the flexible foil (6) is detachably secured, on the side of the insulating layer (3), to another substrate (9), after which the conductor pattern (4) is formed in the conductive layer (4), whereafter the flexible foil (6) is detachably secured, on the side of the conductive layer (4), to the substrate (7), after which the other substrate (9) is removed.

4. (amended) A method as claimed in ~~any one of the preceding claims~~claim 1, characterized in that a number of semiconductor bodies (1) are simultaneously formed so as to be connected to each other, and subsequently secured, on a side opposite the connection regions (2), to an elastic foil (11), after which they are separated by means of sawing or etching, whereafter the elastic foil (11) is stretched uniformly in all directions after which the individual semiconductor bodies (1) are provided and secured onto the flexible foil (6).

5. (amended) A method as claimed in ~~any one of the preceding~~
~~claims~~claim 1, characterized in that prior to the provision of the
semiconductor body (1) on the flexible foil (6), a part thereof
that is situated between the apertures (5) in the insulating layer
(3) is provided with an electrically insulating fixing agent (12)
on which the semiconductor body (1) is placed and the height of
which determines the distance between the semiconductor body (1)
and the flexible foil (6).

6. (amended) A method as claimed in ~~any one of the preceding~~
~~claims~~claim 1, characterized in that after the provision of the
semiconductor body (1) on the flexible foil (6), a liquid,
electrically insulating synthetic resin (13) is provided between
the semiconductor body (1) and the flexible foil (6) as well as
around the semiconductor body (1), which synthetic resin is
subsequently cured.

8. (amended) A method as claimed in ~~any one of the preceding~~
~~claims~~claim 1, characterized in that a solid photoresist layer (3)
is used for the electrically insulating layer (3).

9. (amended) A method as claimed in ~~any one of the preceding~~
~~claims~~claim 1, characterized in that for the material of the

